Wire Wound Chip Inductor
-YWIF3225 Series

■ Features

- Minature size,suitable for SMT.
- Using terminal electrode structure to restrain the parasitic component effect quite caused by lead.
- Execellent in solderability and heat resistance.
- Best frequency special property and intense ability to resist interference.
- Operating temperature:-40℃ ~ +85℃.

■ Applications

- Protable communication equipment and PDA,high speed electronic device.
- Used for radiation high speed noise suppression.

■ Product Identification

YWIF □□□□ - □□□ - □

(1) (2) (3) (4)

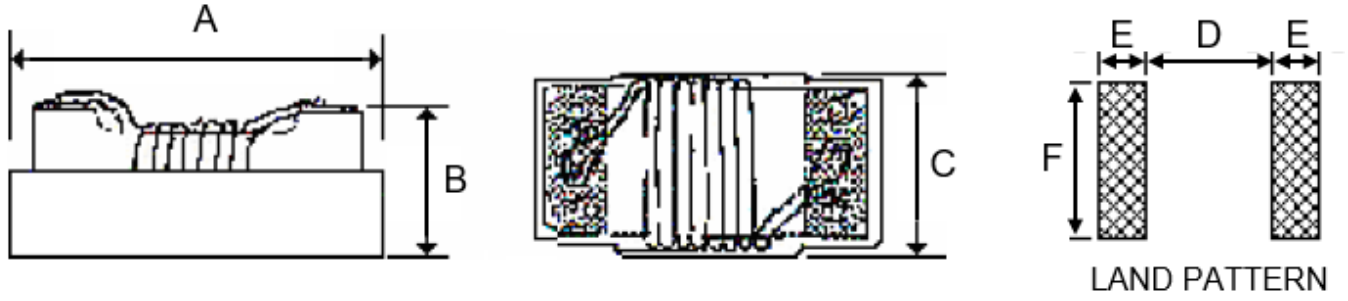
(1)： Type

(2)： Dimensions

(3)： Inductance value

(4)： Inductance Tolerance: M=±20%,K=±10%,J=±5%

■ Shapes and Dimensions (Unit：mm)



TYPE	A Max.	B Max.	C Max.	D Typ.	E Typ.	F Typ.
YWIF3225	3.50	2.25	2.90	1.78	1.02	2.54

■ YWIF3225 Series

Part Number	L (uH)	Freq. (MHz)	Q Min.	SRF Min. (MHz)	Rdc Max. (Ω)	Irms Max. (mA)
YWIF3225-R56K	0.56±10%	25	20	180	0.55	450
YWIF3225-R82K	0.82±10%	7.9	20	200	0.40	450
YWIF3225-1R0K	1.0±10%	7.9	20	200	0.40	450
YWIF3225-1R2K	1.2±10%	7.9	20	200	0.40	450
YWIF3225-1R5K	1.5±10%	7.9	20	200	0.40	450
YWIF3225-1R8K	1.8±10%	7.9	20	195	0.80	450
YWIF3225-2R2K	2.2±10%	7.9	30	175	0.80	450
YWIF3225-3R3K	3.3±10%	7.9	20	150	1.20	400
YWIF3225-4R7K	4.7±10%	7.9	18	60	1.30	350
YWIF3225-5R6K	5.6±10%	7.9	18	50	2.00	320
YWIF3225-6R8K	6.8±10%	7.9	18	35	1.50	310
YWIF3225-8R2K	8.2±10%	7.9	15	33	1.60	305
YWIF3225-100K	10±10%	2.5	15	30	1.00	300
YWIF3225-120K	12±10%	2.5	15	25	1.80	300
YWIF3225-150K	15±10%	2.5	15	22	2.00	225
YWIF3225-180K	18±10%	2.5	15	22	2.05	215
YWIF3225-220K	22±10%	2.5	15	20	2.40	210
YWIF3225-270K	27±10%	2.5	15	20	2.80	160
YWIF3225-330K	33±10%	2.5	15	15	2.90	160
YWIF3225-470K	47±10%	2.5	15	10	5.20	140
YWIF3225-560K	56±10%	2.5	8	8	5.60	125
YWIF3225-680K	68±10%	1	6	10	13.00	100
YWIF3225-820K	82±10%	1	6	10	13.00	100
YWIF3225-101K	100±10%	1	6	10	13.00	100

■ YWIF3225 Series

Part Number	L (uH)	Freq. (MHz)	Q Min.	SRF Min. (MHz)	Rdc Max. (Ω)	Isat Max. (mA)
YWIF3225-221K	220±10%	1	8	2.6	30.00	65
YWIF3225-331K	330±10%	1	8	2.3	35.00	55
YWIF3225-471K	470±10%	1	8	2	42.00	40
YWIF3225-561K	560±10%	1	8	3	60.00	10
YWIF3225-621K	620±10%	1	8	2	85.00	10
YWIF3225-681K	680±10%	1	6	2	90.00	10

※ Rating DC current:temperature rise(ΔT) is 40 ℃ approximately at Irms.

※ Saturation DC current:Inductance drop approximately 30% of L0 at Isat.

※ Storage temp.:-10℃ ~ + 40℃ R.H.:65% Max.

※ Moisture sensitivity level(MSL)2(1 year floor life at<30℃/65% relative humidity).

■ Soldering Conditions

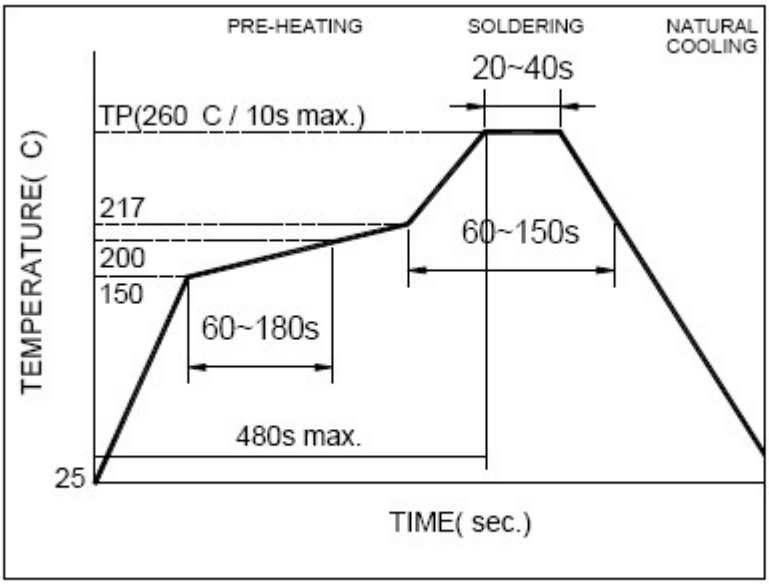


Figure 1. Re-flow Soldering (Lead Free)

Note:
- Preheat circuit and products to 150℃
- 260℃ tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

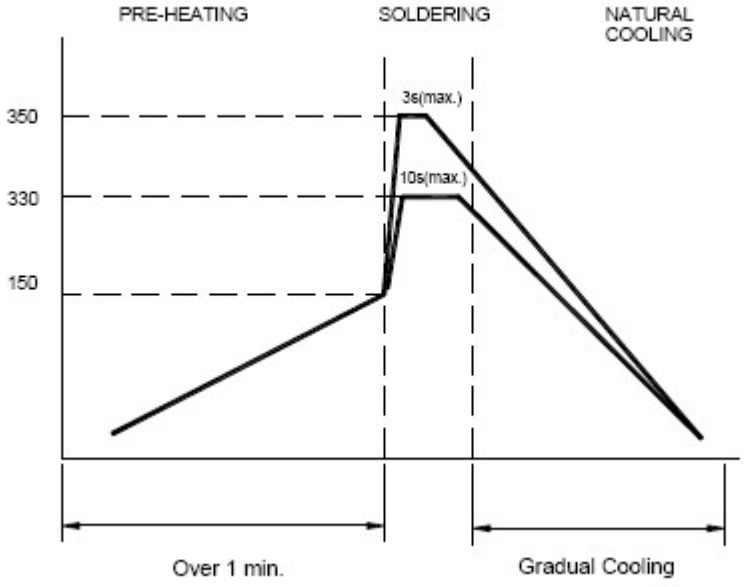
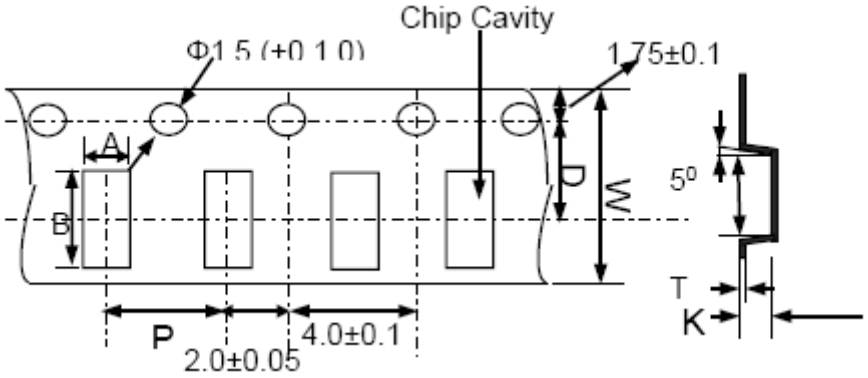


Figure 2. Hand Soldering

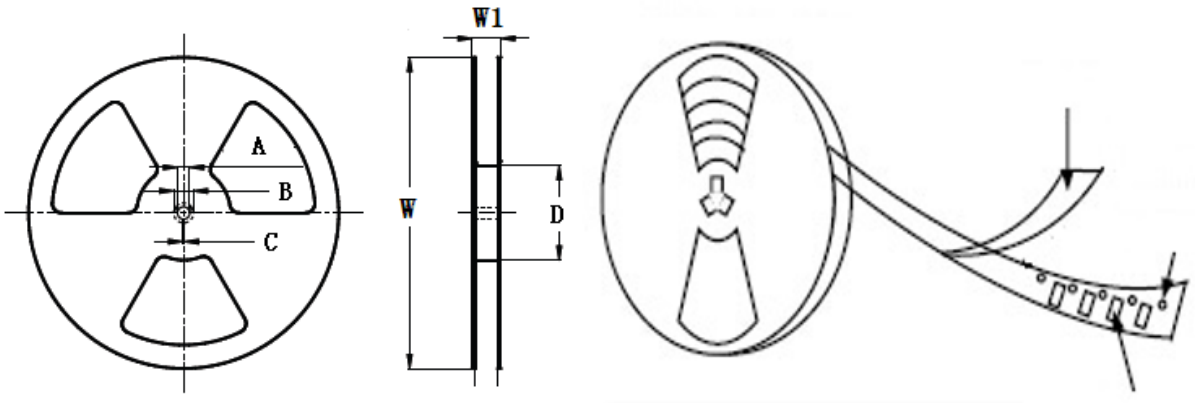
Note:
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

■ Taping Dimensions(Unit:mm)



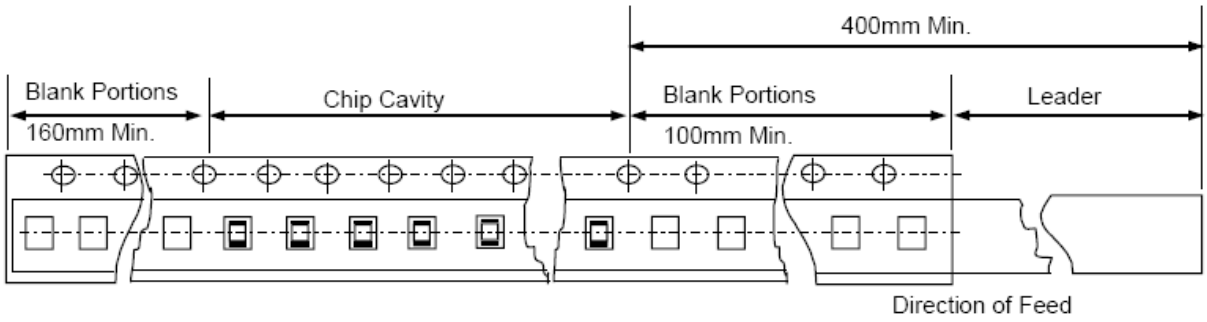
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YWIF3225	8.00	1.50	2.30	3.50	4.00	1.10	0.30	2000

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	A	B	C	D
YWIF3225	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

■ Leader and Blank portion



1．Missing chips number within 0.1% of the number per reel or 1pcs, whichever is greater, and are not continuous.

2．The top tape and bottom tape shall not protrude beyond the edges of the tape and shall not cover sprocket hole.

3．Cumulative tolerance of sprocket holes, 10 pitches: ±0.3mm.

4．Peeling off force: 10gf to 100gf in the direction show below for 8mm carrier tapes and 10gf to 130gf for 12mm to 56mm wide carrier tapes.

